

BSI NATIONAL ACCIDENTATION OF CERTIFICATIONS 10000S

7FL., NO.17, LANE 3, SEC.1 CHUNG CHENG EAST RD., TAMSHUI, TAIPEI, TAIWAN, R.O.C. TEL: 886-2-2629-9955 (REP) FAX: 886-2-2626-6677

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Type Document	Product Specification	Revised / Edition	D
Date Issued	2004/12/31	Data Revised	2015/04/03
Subject: JS-1225-XX JS-1225-T JS-1235R-XX-HK Pitch 1.25mm Wire to Board SMT Series Connector			Issued By: Engineering Dept.

This specification is referred to the 1.25mm SMT series wire to board connector.

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Pitch 1.25mm	Wire to Board SMT Sei	ries Connector	Engineering Dept.

1.0 Product Name/Part Number & Drawing Number:

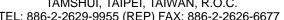
Product Name		Part Number	Drawing Number
Ter	minal	JS-1225-T	JS-1225-T
Housing		JS-1225-XX	JS-1225- XX
	5:	JS-1235R-XX	JS-1235R- XX
Wafer	Right Angle	JS-1235R-XX-HK	JS-1235R- XX-HK

Note: (xx) The number of the circuits.

2.0 Construction/Dimensions/Material & Surface Finish: Construction and dimensions shall be in accordance with the referenced drawing. Material and surface finish shall be specified as listing.

Part Name		Material	Surface Finish
Crimp To	erminal	Phosphor Bronze	Tin-Plated Gold-Plated
Hous	sing	Nylon 66	UL 94V-0
	Contact	Brass	Tin-Plated
Wafer	Wafer Solder Tab		
	Base	PA 9T LCP&PPA(Halogen Free)	UL 94V-0







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3.0 Characteristic:

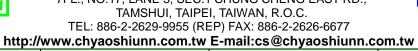
Item		Standard				
3.1	Rated Current		1A AC/DC (With AWG #28 is applied)			
3.2	Rated Voltage		100V AC/DC			
3.3	Ambient Temperature Range	Operating Temp.: -25~+85; Including 30°C Terminal Temperature Rise at rated Current . Storage temp.: -25~+85;				
2.4	Appliachle Wire	3.4.1	Conductor Construction Size: AWG #28~#32			
3.4	3.4 Applicable Wire		Wire Insulation O.D.: 0.6mm~1.13mm			
		3.5.1	SMT Layout: 1.25 ± 0.05 mm per Pitch			
2.5	3.5 Applicable Printed Circuit Board (PCB)	3.5.2	SMT Layout: 2.0X0.7±0.05 mm for Pin Post			
3.5		3.5.3	SMT Layout: 2.6X2.0±0.05 mm for Ear Buckle			
			SMT Layout: ∮ 1.1±0.05 mm for pillar			

4.0 Specimen:

Part Name/ Part Number/ Picture or Photograph						
Housing JS-1225- XX		Wafer Right Angle JS-1235R-XX				
Crimp Terminal JS-1225-T		Wafer Right Angle JS-1235R- XX-HK	THE PROPERTY.			



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5.0 Applicable Standards:

MIL-STD-202 Methods by test of connectors for electronic equipment. **EIA 364 Testing method for electrical connectors.**

6.0 Mechanical Performance:

	Item	Test Con	dition	Requirement
6.1	Insertion & Retention Force	Insert and withdraw wit speed rate of 25mm/min (EIA 364-13)	Refer to paragraph 9.1	
		5 II	AWG#28 size wire	1.3kgf/Min.
6.2	6.2 Crimp Tensile Strength	Pull with contact terminal at the speed rate of 25mm/minute.	AWG#30size wire	0.8kgf/Min.
			AWG#32 size wire	0.6kgf/Min.
6.3		Withdraw with contact to rate of 25mm/minute.	0.5kgf/Min.	
6.4	Post Retention Force	Use a tension gauge to speed rate of 25mm/min (EIA 364-29C)	0.5kgf/Min.	







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7.0 Electrical Performance:

	Item	Test Condition	Requirement
7.1	Contact Resistance	A maximum voltage of 20mV and a maximum current of 10mA are applied to the Mate connectors. (EIA 364-23)	Contact Resistance: 20 milliohms Max.
7.2	Current Continuity	Each circuit of the connector shall be connected in series. Continuity meter shall inspect current discontinuity.	No discontinuity current is longer than 1 microsecond.
7.3	Insulation Resistance	Apply 500V D/C to any two adjacent contacts to measure the insulation resistance. (EIA 364-21)	Insulation Resistance: Initial 500megohms Min.
7.4	Withstanding Voltage	Apply 500V A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent terminal and ground of the Mate connectors. (EIA 364-20)	No breakdown or flashover.



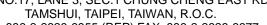


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8.0 Environmental Performance:

Item		Test Condition	Requirement
8.1	Vibration	Frequency: 10~55~10 Hz/minute. Amplitude: 1.52 mm. Direction: 1. Axis of up and down.	Contact Resistance: 40 milliohms Max. after the test.
		2. Axis of right the left. 3. Axis of front and back. Period: 2 hours for each direction. (EIA 364-28A-23)	No discontinuity current is longer than 1 microsecond.
			Contact Resistance: 40 milliohms Max. after the test.
8.2	Humidity Steady State	Temperature: 40±2℃. Humidity: 90%~95% (RH). Period: 96 hours continuously.	Insulation Resistance: 100 megohms Min. after the test.
		(EIA 364-31)	Withstanding Voltage: No breakdown or flashover. after the test.
		Temperature: 85±2℃.	Contact Resistance:
8.3	Heat Aging	Period: 96 hours continuously. (EIA 364-17)	40 milliohms Max. after the test.







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Item		Test Condition	Requirement	
8.4	Thermal Shock	One Cycle Consists Of: -55 +0/-3°C for 30 minutes. → Room Temp.5 minutes 85+3/-0°C for 30 minutes. → Room Temp.5 minutes Total Cycles: 25 Cycles. (EIA 364-32)	Same as paragraph 8.2	
8.5	Salt Spray	Temperature: 35±2℃. Density: 5 % in weight. Period: Terminal or contact (Stamping after tin plated for 8 hours); Terminal or contact (Stamping before tin plated for 24 hours)	Contact Resistance: 40 milliohms Max. after the test.	
8.7	Solder Ability	Solder Temperature: 245 ± 5℃. Immersion Period: 3±0.5 Seconds Method: 1.5mm From Square Pin Tip. (EIA 364-52)	Solder entirely 95% of immersed area must show no voids or pinholes.	



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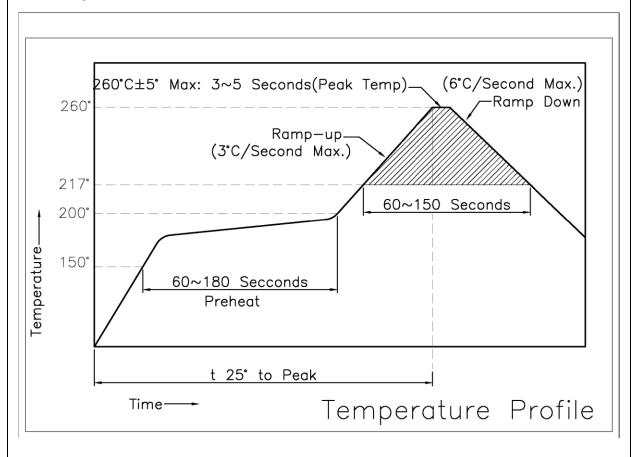
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Item Test Condition Requirement By reflow soldering: Refer to Temperature Profile 8.8.1 Not deformation or damage. 8.8 Resistance To Soldering Heat By soldering iron: 350 ± 5 °C 3±0.5 Seconds. Method: 0.5mm From Terminal Tip and Solder Tab Tip				
Refer to Temperature Profile 8.8.1 Resistance To Soldering Heat By soldering iron: 350 ± 5°C 3±0.5 Seconds. Method: 0.5mm From Terminal Tip and		Item	Test Condition	Requirement
	8.8	To Soldering	Refer to Temperature Profile 8.8.1 By soldering iron: 350 ± 5℃ 3±0.5 Seconds. Method: 0.5mm From Terminal Tip and	

8.8.1 Temperature Profile:





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9.0 Insertion Force (I.F.) & Retention Force (R.F.)

9.1 Requirement:

No. Of	AT INITIAL		AT 50TH	No. Of	AT INITIAL		AT 50TH
	I.F. (MAX)	R.F. (MIN)	R.F. (MIN)		I.F. (MAX)	R.F. (MIN)	R.F. (MIN)
				11	8.80	1.10	0.88
02	1.60	0.20	0.16	12	9.60	1.20	0.96
03	2.40	0.30	0.24	13	10.40	1.30	1.04
04	3.20	0.40	0.32	14	11.20	1.40	1.12
05	4.00	0.50	0.40	15	12.00	1.50	1.20
06	4.80	0.60	0.48	16	12.80	1.60	1.28
07	5.60	0.70	0.56	17	13.60	1.70	1.36
08	6.40	0.80	0.64	18	14.40	1.80	1.44
09	7.20	0.90	0.72	19	15.20	1.90	1.52
10	8.00	1.00	0.80	20	16.00	2.00	1.60

(Kg/f)

- 10.0 Caution: Parts are made of hydrophilic Polyamide 9T and apt to absorb moisture. Once the vacuum-packing unpacked, please keep parts in the environment of temperature < 30 °C/ humidity < 60% RH, and send to re-flowing within 72 hours to prevent parts blistered or deformed during soldering.
 - 11.0 Remark: Any change or revision for the product specification will not be announced in advance. Please contact our sales representative for the latest information.

Reviewed:	Dicky_Tang	Approved:	Liuzhiwen	Verified:	Sunquan	
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